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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DATASHEET

Technical Data Sheet
1.6mm round Subminiature Side Looking Infrared
LED
EAISV3024A0

Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel.
- Pb free
- The product itself will remain within RoHS compliant version.

Description

• EAISV3024A0 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens. The device is spectrally matched with silicon photodiode and phototransistor

Applications

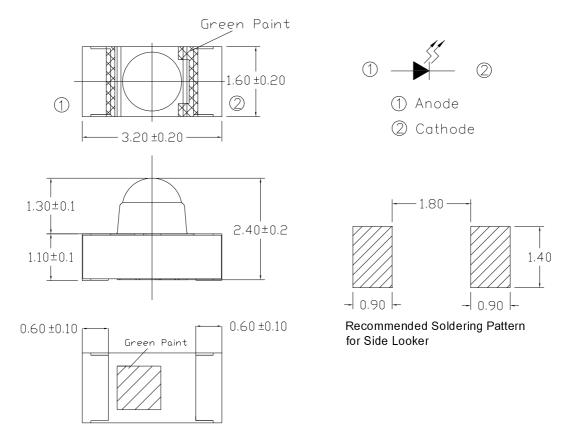
• Infrared applied system

Device Selection Guide

LED Dowt No	Chip	Lens Color	
LED Part No.	Material		
EAISV3024A0	GaAlAs	Water Clear	



Package Dimensions



Notes: 1. All dimensions are in millimeters

2. Tolerances unless dimensions ±0.1mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I_{F}	65	mA
Reverse Voltage	V_R	5	V
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\!\mathbb{C}$
Soldering Temperature *2	T _{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	100	mW

Notes: *1: Soldering time ≤ 5 seconds..



Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
		2.0	4.5		mW /sr	I _F =20mA
Radiant Intensity	Ie		22			I_F =100mA Pulse Width \leq 100 μ s ,Duty \leq 1%
Peak Wavelength	λр		940		nm	I _F =20mA
Spectral Bandwidth	Δλ		30		nm	I _F =20mA
Forward Voltage	V_{F}		1.25	1.5	V	I _F =20mA
			1.4	1.8		$I_F=100 mA$ Pulse Width $\leq 100 \mu \text{ s ,Duty} \leq 1\%$
Reverse Current	I_R			10	μ A	$V_R=5V$
View Angle	$2\theta_{1/2}$		45		deg	I _F =20mA

Ie Rank

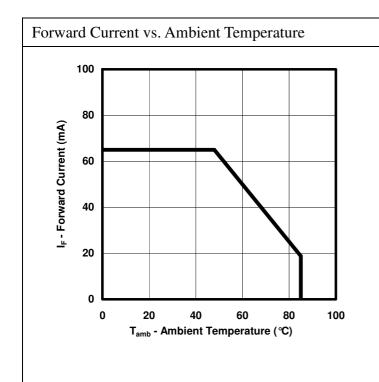
 $Condition : I_F \!\!=\!\! 20mA$

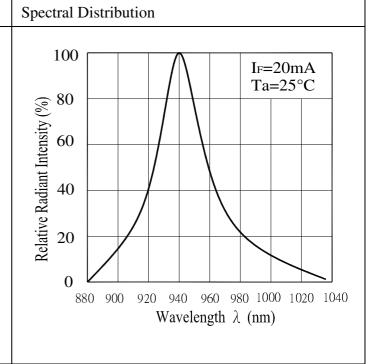
Unit: mW/sr

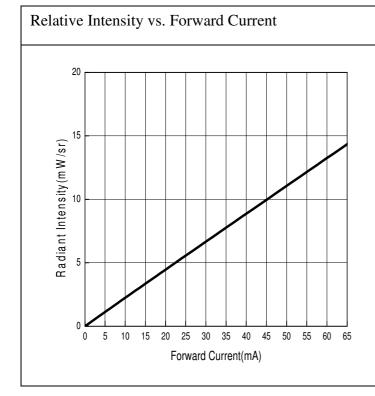
Bin Number	Н	J	K	L
Min	2.0	3.0	4.0	5.0
Max	3.5	4.5	6.0	

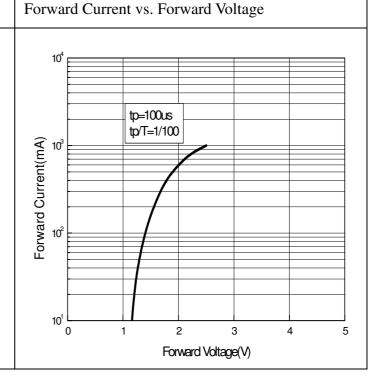


Typical Electrical/Optical/Characteristics Curves for IR

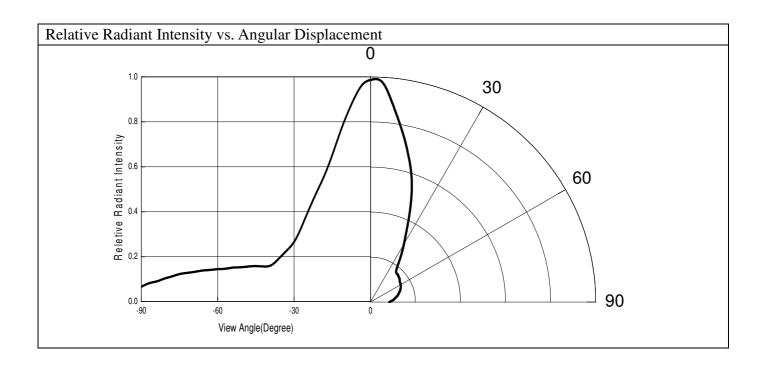














Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

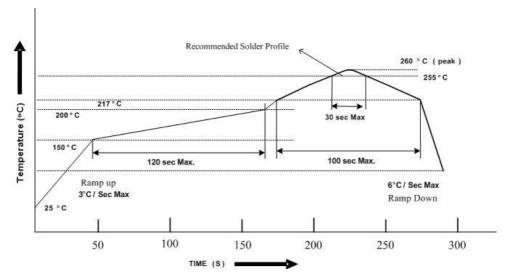
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30° C or less and 70%RH or less.
- 2.5 The LEDs should be used within 72 hours (3 days) after opening the package
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : $60\pm5^{\circ}$ C for Min. 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

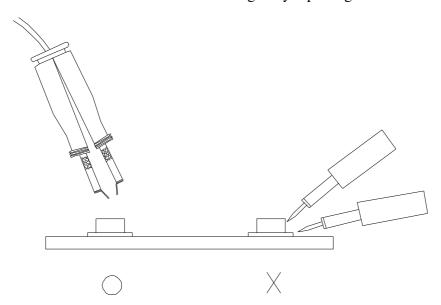


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

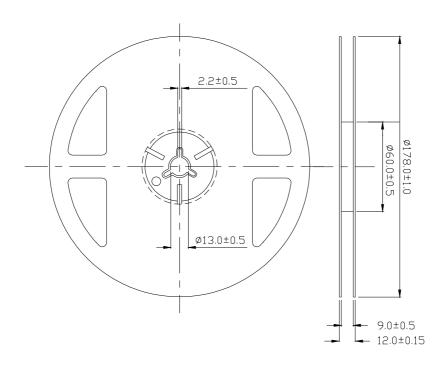
5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



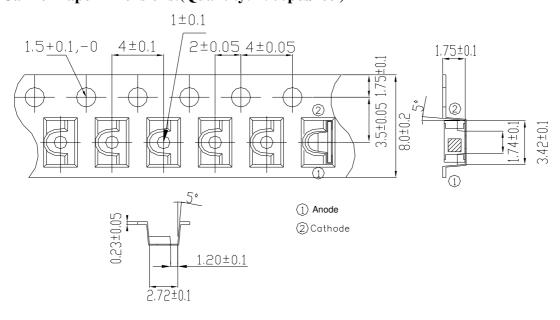


Package Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

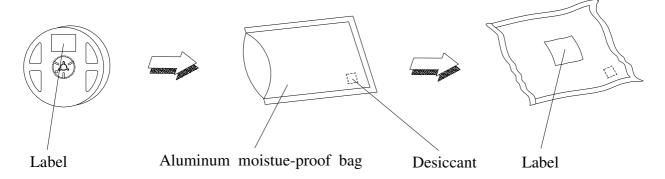
Carrier Tape Dimensions:(Quantity: 1500pcs/reel)



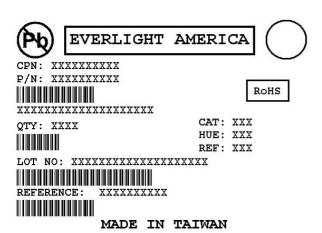
Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm



Packing Procedure



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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